

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:  
a semiconductor chip having pads formed thereon;  
a flexible insulation substrate with conductor  
5 patterns formed thereon; and  
a sealing resin,  
wherein the conductor patterns protrude into an  
opening defined in the flexible insulation substrate and are  
coupled to the semiconductor chip in a coupling section, the  
10 coupling section being sealed by the sealing resin, and  
wherein at least one of the conductor patterns  
extends across the opening and has a width wider than a  
width of one of the pads of the semiconductor chip.
2. The semiconductor device according to claim 1,  
15 wherein the conductor pattern extending across the opening  
has at least one bent section.
3. An electronic device comprising the semiconductor  
device according to claim 1.
4. A semiconductor device comprising:  
20 a semiconductor chip having pads formed thereon;  
a flexible insulation substrate with conductor  
patterns formed thereon; and  
a sealing resin,  
wherein the conductor patterns protrude into an  
25 opening defined in the flexible insulation substrate and are  
coupled to the semiconductor chip in a coupling section, the  
coupling section being sealed by the sealing resin, and  
wherein at least one of the conductor patterns  
extends across the opening and has at least one connection



10. The semiconductor device according to claim 8, wherein the conductor pattern connecting to the power source electrode or the grounding electrode has at least one connection branch.

5 11. The semiconductor device according to claim 10, wherein the connection branch has a width narrower than a width of the power source electrode or of the grounding electrode.

10 12. The semiconductor device according to claim 10, wherein the connection branch has a tip section connected to the flexible insulation substrate.

13. The semiconductor device according to claim 9, wherein the conductor pattern extending across the opening has at least one bent section.

15 14. An electronic device comprising the semiconductor device according to claim 8.

15. A semiconductor device comprising:

a semiconductor chip having pads formed thereon;

20 a flexible insulation substrate with conductor patterns formed thereon; and

a sealing resin,

25 wherein the conductor patterns protrude into an opening defined in the flexible insulation substrate and are coupled to the semiconductor chip in a coupling section, the coupling section being sealed by the sealing resin, and

wherein at least one of the conductor patterns extends across the opening and has at least one branch, the branch having a tip section connected to the flexible insulation substrate.

16. The semiconductor device according to claim 15,  
wherein the branch is connected to the semiconductor chip.

17. The semiconductor device according to claim 15, wherein the conductor pattern extending across the opening has at least one bent section.

18. The semiconductor device according to claim 15, wherein the branch has a width narrower than a width of one of the pads of the semiconductor chip.

19. An electronic device comprising the semiconductor device according to claim 15.

20. A tape carrier package type semiconductor device comprising:

a semiconductor chip having pads formed thereon;  
a tape carrying the semiconductor chip, the tape  
having a device hole; and

conductor patterns for power source and grounding, each of the conductor patterns traversing the device hole and having at least one branched connection inner lead, the branched connection inner lead having a width narrower than a width of one of the pads of the semiconductor chip for connecting the conductor pattern to the semiconductor chip.

21. The semiconductor device according to claim 20, wherein the branched connection inner lead has a tip section connected to the tape.

22. The semiconductor device according to claim 20,  
wherein each of the conductor patterns for power source and  
grounding has at least one bent section.

23. An electronic device comprising the semiconductor device according to claim 20.

**SECRET**

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